

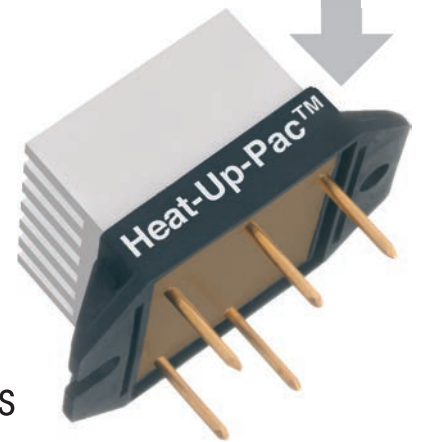
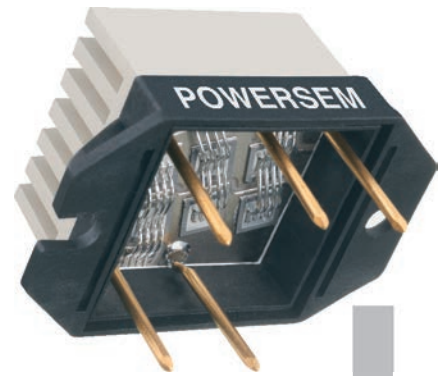
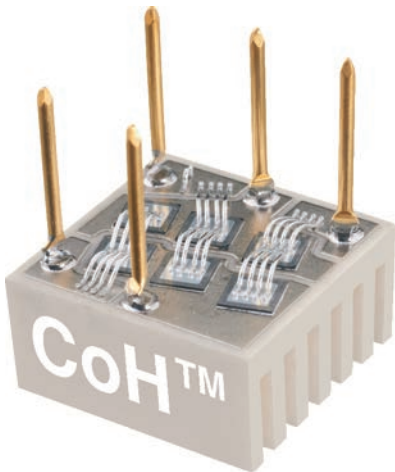
# POWERSEM

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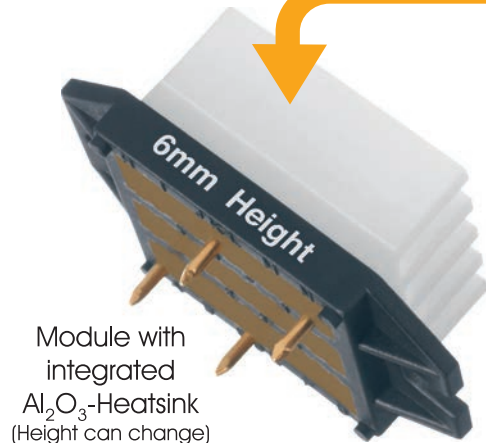


**NEW**

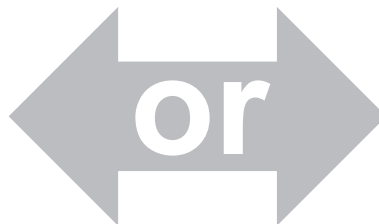
## Heat-Up-Pac™

- Integrated Heatsink
- Best Thermal Cycling
- With Press Pins or Solder Pins
- Fast mounting of the Module
- For Si-, SiC-, GaN- and GaAs-Devices

**BEST HEAT TRANSFER**  
with Chip on Heatsink™



Module with integrated Al<sub>2</sub>O<sub>3</sub>-Heatsink (Height can change)



Module with integrated AlN-Heatsink (Height can change)

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**PCIM**  
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